

REMARKS

Reconsideration and allowance are respectfully requested. Claims 1, 5, 7-9, 14, and 15 have been amended. Claims 4, 12 and 17 have been canceled. Claim 18 has been added. Thus, claims 1-3, 5-11, 13-16, and 18 are pending.

The election of Group I, claims 1-16 is hereby affirmed. Non-elected claim 17 has been canceled.

Claims 1, 2, 3, 8, 9, 10, 11, 13, 15 and 16 stand rejected under 35 U.S.C. 102(b) as being anticipated by Moskob. Claims 1 and 9 have been amended to obviate the rejection. In particular, each of claims 1 and 9 has been amended to recite lead structure having leads constructed and arranged to be coupled with a source of power to power the motor. The lead structure has ends and leg portions connecting the leads to the ends. The ends of the lead structure are soldered to the printed circuit board, with the legs portions being generally parallel with the printed circuit board. As noted in the specification, the location of the PCB 26, close to and parallel to the legs 25 of the leads 24, utilizes already available space, and provides for soldering the PCB 26 directly to the lead ends 36 that greatly improves the effectiveness of the EMI suppression components. Moskob does not teach or suggest such structure. Therefore, the rejection of claims 1 and 9, and the claims that depend there-from should be withdrawn.

Claims 4 and 12 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Moskob in view of Tarnow et al. These claims depend from claim 1 and 9, respectively, and are considered to be allowable for the reasons advanced above, and for the additional reason that the added subject matter thereof is not taught or suggested by the prior art of record.

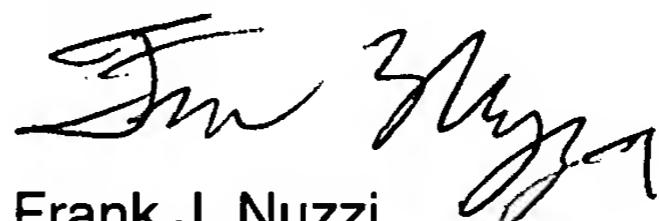
Claims 5-7 and 14 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Moskob in view of Adams et al. This rejection is respectfully traversed. In addition, claims 5 and 14 have been amended to recite that the cover is over-molded to cover an entire surface of the printed circuit board. Adams et al. do not show a circuit board, let alone an over-molded cover. Adams et al. merely disclose a casting compound 35 that is injected to encase certain components other than a circuit board 33. Furthermore, one could not over-mold a cover to cover an entire surface of the circuit board 33 of

Moskob since the left side portion of the circuit board that includes the RFI suppression member 55 is not accessible for over-molding. In addition, Moskob teaches a cover 31 that covers only a right side portion of the circuit board 33 that is above the electronics 4. There would be no need to over-mold a cover at the left side of the circuit board 33 since this portion is already covered by the transmission housing 20. Therefore, the rejection is improper and should be withdrawn.

Claim 18 has been added and is considered to be allowable for the reasons advanced above with regard to claim 5.

All rejections having been addressed, it is respectfully submitted that this application is in condition for allowance and a Notice to that effect is earnestly solicited.

Respectfully submitted,



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